



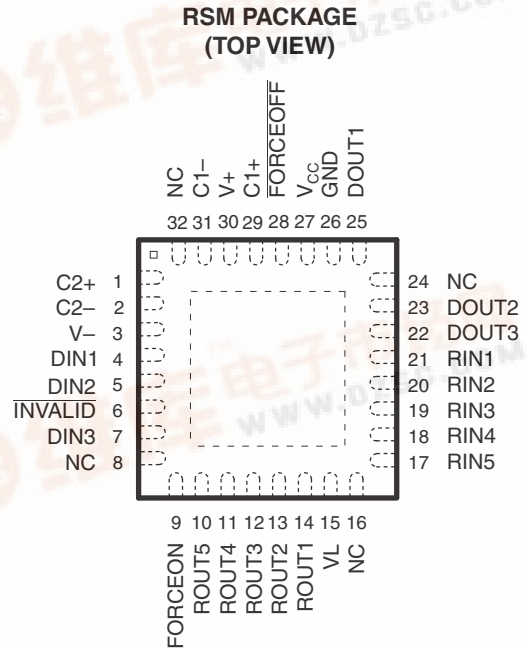
RS-232 TRANSCEIVER WITH SPLIT SUPPLY PIN FOR LOGIC SIDE

FEATURES

- V_L Pin for Compatibility With Mixed-Voltage Systems Down to 1.8 V on Logic Side
- Enhanced ESD Protection on RIN Inputs and DOUT Outputs
 - ± 8 kV IEC 61000-4-2 Air-Gap Discharge
 - ± 8 kV IEC 61000-4-2 Contact Discharge
 - ± 15 kV Human-Body Model
- Low 300- μ A Supply Current
- Specified 1000-kbps Data Rate
- Auto Powerdown Plus Feature

APPLICATIONS

- Hand-Held Equipment
- PDAs
- Cell Phones
- Battery-Powered Equipment
- Data Cables



NC – No internal connection

DESCRIPTION/ORDERING INFORMATION

The TRS3253E is a three-driver and five-receiver RS-232 interface device, with split supply pins for mixed-signal operations. All RS-232 inputs and outputs are protected to ± 8 kV using the IEC 61000-4-2 Air-Gap Discharge method, ± 8 kV using the IEC 61000-4-2 Contact Discharge method, and ± 15 kV using the Human-Body Model.

The charge pump requires only four small 0.1- μ F capacitors for operation from a 3.3-V supply. The TRS3253E is capable of running at data rates up to 1000 kbps, while maintaining RS-232-compliant output levels.

The TRS3253E has a unique V_L pin that allows operation in mixed-logic voltage systems. Both driver in (DIN) and receiver out (ROUT) logic levels are pin programmable through the V_L pin. This eliminates the need for additional voltage level shifter while interfacing with low-voltage microcontroller or UARTs. The TRS3253E is available in a space-saving QFN package (4 mm \times 4 mm RSM).

Auto-powerdown plus can be disabled when FORCEON and $\overline{\text{FORCEOFF}}$ are high. With auto-powerdown plus enabled, the device activates automatically when a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μ s. INVALID is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 μ s. Refer to Figure 5 for receiver input levels.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RSM	TRS3253ERSMR	RS53EI

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



FUNCTION TABLES

Each Driver⁽¹⁾

INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown plus disabled
H	H	H	X	L	
L	L	H	<30 s	H	Normal operation with auto-powerdown plus enabled
H	L	H	<30 s	L	
L	L	H	>30 s	Z	Powered off by auto-powerdown plus feature
H	L	H	>30 s	Z	

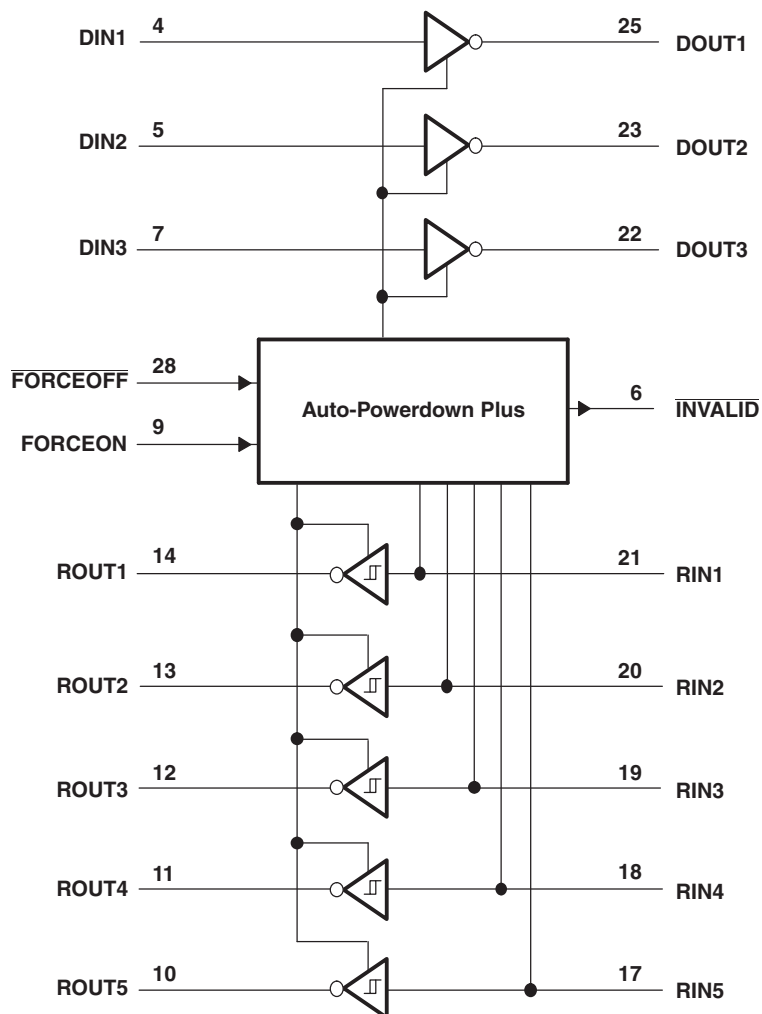
(1) H = high level, L = low level, X = irrelevant, Z = high impedance

Each Receiver⁽¹⁾

INPUTS			OUTPUTS	RECEIVER STATUS
RIN1–RIN5	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	ROUT1-ROUT5	
X	L	X	Z	Powered off
L	H	<30 s	H	Normal operation with auto-powerdown plus disabled/enabled
H	H	<30 s	L	
Open	H	<30 s	H	

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

FUNCTIONAL BLOCK DIAGRAM



PRODUCT PREVIEW

TERMINAL FUNCTIONS

TERMINAL		DESCRIPTION
NAME	RSM	
C1+, C2+	29, 1	Positive terminal of the voltage-doubler charge-pump capacitor
V+	30	5.5-V supply generated by the charge pump
C1–, C2–	31, 2	Negative terminal of the voltage-doubler charge-pump capacitor
INVALID	6	Invalid Output Pin
V–	3	–5.5-V supply generated by the charge pump
DIN1 DIN2 DIN3	4 5 7	Driver inputs
ROUT5 - ROUT1	10, 11, 12, 13, 14	Receiver outputs. Swing between 0 and V _L .
V _L	15	Logic-level supply. All CMOS inputs and outputs are referenced to this supply.
RIN5-RIN1	17, 18, 19, 20, 21	RS-232 receiver inputs
DOUT3 DOUT2 DOUT1	22 23 25	RS-232 driver outputs
GND	26	Ground
V _{CC}	27	3-V to 5.5-V supply voltage
FORCEOFF	28	Powerdown Control input (Refer to Truth Table)
FORCEON	9	Powerdown Control input (Refer to Truth Table)

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC} to GND			−0.3	6	V
V _L to GND			−0.3	V _{CC} + 0.3	V
V+ to GND			−0.3	7	V
V− to GND			0.3	−7	V
V+ + V− ⁽²⁾				13	V
V _I	Input voltage	DIN, $\overline{\text{FORCEOFF}}$ to GND, FORCEON to GND	−0.3	6	V
		RIN to GND		±25	
V _O	Output voltage	DOUT to GND		±13.2	V
		ROUT	−0.3	V _L + 0.3	
Continuous power dissipation		T _A = 70°C, 32-pin RSM (derate 7 mW/°C above 70°C)		TBD	mW
T _J	Junction temperature			150	°C
T _{stg}	Storage temperature range		−65	150	°C
Lead temperature (soldering, 10 s)				300	°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

(2) V+ and V– can have maximum magnitudes of 7 V, but their absolute difference cannot exceed 13 V.

RECOMMENDED OPERATING CONDITIONS

			MIN	MAX	UNIT
V _{CC}	Supply voltage		3	5.5	V
V _L	Supply voltage		1.65	V _{CC}	V
Input logic threshold low	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	V _L = 3 V or 5.5 V	0.8		V
		V _L = 2.3 V	0.6		
		V _L = 1.65 V	0.5		
Input logic threshold high	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	V _L = 5.5 V	2.4		V
		V _L = 3 V	2.0		
		V _L = 2.7 V	1.4		
		V _L = 1.95 V	1.25		
Operating temperature	TRS3253ECPWR		0	70	°C
	TRS3253EIPWR		−40	85	
Receiver input voltage			−25	25	V

ELECTRICAL CHARACTERISTICS⁽¹⁾

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V to }5.5\text{ V}$, $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C1 = 0.047\text{ }\mu\text{F}$, $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$) (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
I_I	Input leakage current	$\overline{FORCEOFF}$, $FORCEON$		± 0.01	± 1	μA
I_{CC}	Supply current ($T_A = 25^\circ\text{C}$)	Auto-powerdown plus disabled	No load, $\overline{FORCEOFF}$ and $FORCEON$ at V_{CC}		0.5	1 mA
		Powered off	No load, $\overline{FORCEOFF}$ at GND		1	10
		Auto-powerdown plus enabled	No load, $\overline{FORCEOFF}$ at V_{CC} , $FORCEON$ at GND, All RIN are open or grounded		1	10 μA

(1) Testing supply conditions are $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ at $V_{CC} = 3.3\text{ V} \pm 0.15\text{ V}$; $C1\text{--}C4 = 0.22\text{ }\mu\text{F}$ at $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$; and $C1 = 0.047\text{ }\mu\text{F}$ and $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ at $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$.

(2) All typical values are at $V_{CC} = 3.3\text{ V}$ or $V_{CC} = 5\text{ V}$, and $T_A = 25^\circ\text{C}$.

ESD PROTECTION

PARAMETER	TEST CONDITIONS	TYP	UNIT
RIN, DOUT	Human-Body Model	± 15	kV
	IEC 61000-4-2 Air-Gap Discharge	± 8	
	IEC 61000-4-2 Contact Discharge	± 8	

RECEIVER SECTION

Electrical Characteristics

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C1 = 0.047\text{ }\mu\text{F}$, $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$), $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
I_{off}	Output leakage current	R_{OUT} , receivers disabled		± 0.05	± 10	μA
V_{OL}	Output voltage low	$I_{OUT} = 1.6\text{ mA}$			0.4	V
V_{OH}	Output voltage high	$I_{OUT} = -1\text{ mA}$	$V_L - 0.6$	$V_L - 0.1$		V
V_{IT-}	Input threshold low	$T_A = 25^\circ\text{C}$	$V_L = 5\text{ V}$	0.8	1.2	V
			$V_L = 3.3\text{ V}$	0.6	1.5	
V_{IT+}	Input threshold high	$T_A = 25^\circ\text{C}$	$V_L = 5\text{ V}$		1.8 2.4	V
			$V_L = 3.3\text{ V}$		1.5 2.4	
V_{hys}	Input hysteresis			0.5		V
	Input resistance	$T_A = 25^\circ\text{C}$	3	5	7	k Ω

(1) Typical values are at $V_{CC} = V_L = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$

Switching Characteristics

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C1 = 0.047\text{ }\mu\text{F}$, $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$), $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	UNIT
t_{PHL}	Receiver propagation delay	Receiver input to receiver output, $C_L = 150\text{ pF}$	0.15	μs
t_{PLH}			0.15	
$t_{PHL} - t_{PLH}$	Receiver skew		50	ns
t_{en}	Receiver output enable time	From $\overline{\text{FORCEOFF}}$	200	ns
t_{dis}	Receiver output disable time	From $\overline{\text{FORCEOFF}}$	200	ns

(1) Typical values are at $V_{CC} = V_L = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

DRIVER SECTION

Electrical Characteristics

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C1 = 0.047\text{ }\mu\text{F}$, $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$), $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V_{OH} Output voltage swing	All driver outputs loaded with $3\text{ k}\Omega$ to ground, $V_{CC} = 3.1\text{ V}$ to 5.5 V	± 5	± 5.4		V
r_O Output resistance	$V_{CC} = V_+ = V_- = 0$, Driver output = $\pm 2\text{ V}$	300	10M		Ω
I_{OS} Output short-circuit current	$V_{T_OUT} = 0$			± 60	mA
I_{OZ} Output leakage current	$V_{T_OUT} = \pm 12\text{ V}$, $\overline{\text{FORCEOFF}} = \text{GND}$, $V_{CC} = 3\text{ V}$ to 3.6 V			± 25	μA
	$V_{T_OUT} = \pm 12\text{ V}$, $\overline{\text{FORCEOFF}} = \text{GND}$, $V_{CC} = 4.5\text{ V}$ to 5.5 V				
Driver input hysteresis				0.5	V
Input leakage current	DIN, $\overline{\text{FORCEOFF}}$, FORCEON		± 0.01	± 1	μA

(1) Typical values are at $V_{CC} = V_L = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$

Timing Requirements

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C1 = 0.047\text{ }\mu\text{F}$, $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$), $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
Maximum data rate	$R_L = 3\text{ k}\Omega$, $C_L = 200\text{ pF}$, One driver switching	1000			kbps
Time-to-exit powerdown	$ V_{T_OUT} > 3.7\text{ V}$		100		μs
$ t_{PHL} - t_{PLH} $ Driver skew ⁽²⁾			100		ns
Transition-region slew rate	$V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, Measured from 3 V to -3 V or -3 V to 3 V	15		150	V/ μs
	$C_L = 150\text{ pF}$ to 1000 pF				

(1) Typical values are at $V_{CC} = V_L = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Driver skew is measured at the driver zero crosspoint.

AUTO-POWERDOWN SECTION

Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6](#))

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$V_{IT+(valid)}$	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V_L		2.7	V
$V_{IT-(valid)}$	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V_L	–2.7		V
$V_{T(invalid)}$	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V_L	–0.3	0.3	V
V_{OH}	INVALID high-level output voltage	$I_{OH} = -1\text{ mA}$, FORCEON = GND, FORCEOFF = V_L	$V_L - 0.6$		V
V_{OL}	INVALID low-level output voltage	$I_{OL} = 1.6\text{ mA}$, FORCEON = GND, FORCEOFF = V_L		0.4	V

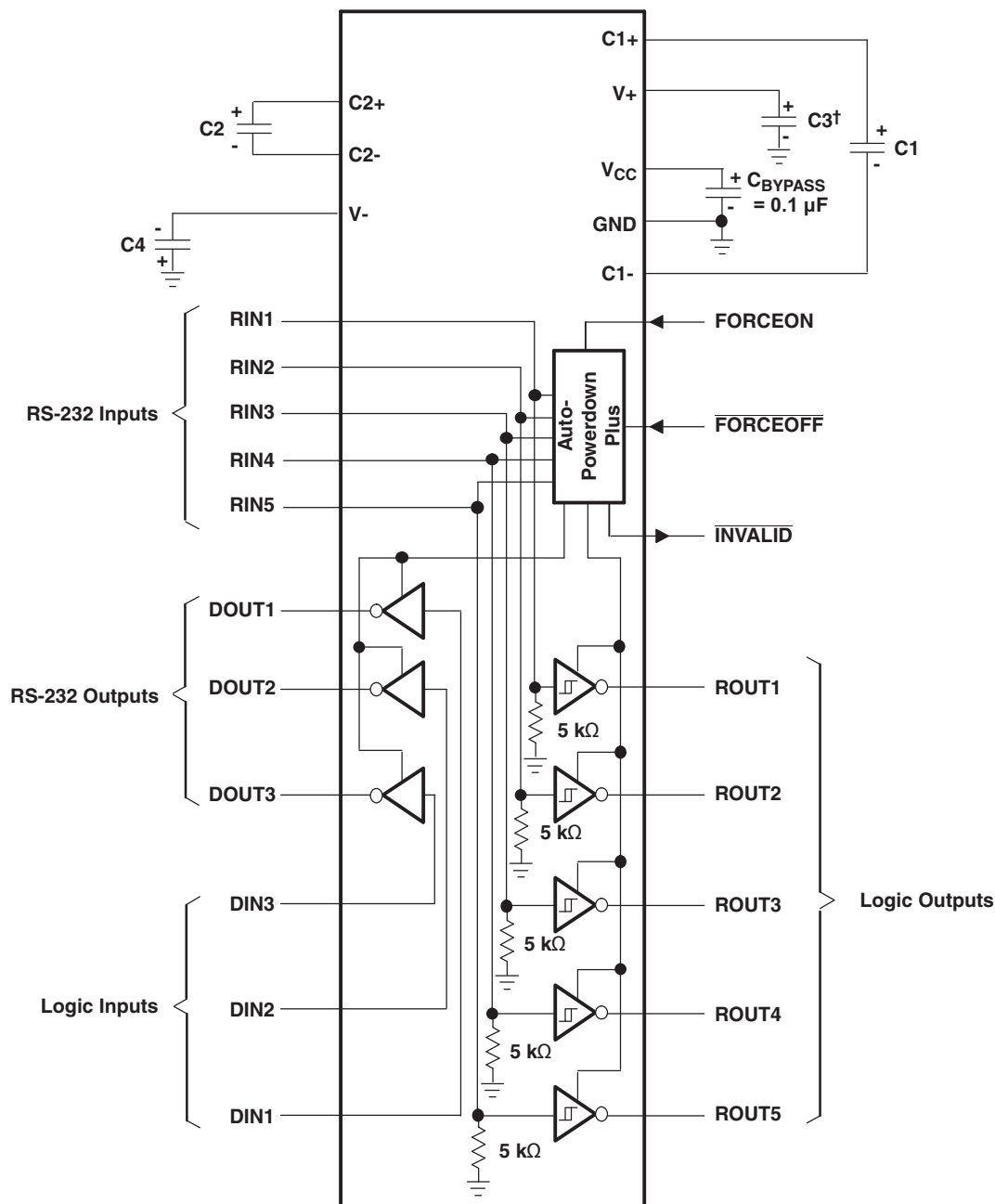
Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6](#))

PARAMETER		MIN	TYP ⁽¹⁾	MAX	UNIT
t_{valid}	Propagation delay time, low- to high-level output		0.1		μs
$t_{invalid}$	Propagation delay time, high- to low-level output		50		μs
t_{en}	Supply enable time		25		μs
t_{dis}	Receiver or driver edge to auto-powerdown plus	15	30	60	s

(1) All typical values are at $V_{CC} = V_L = 3.3\text{ V}$ and $T_A = 25^\circ\text{C}$.

APPLICATION INFORMATION



PRODUCT PREVIEW

† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V _{CC}	C1	C2, C3, and C4
3.3 V ± 0.3 V	0.1 μF	0.1 μF
5 V ± 0.5 V	0.047 μF	0.33 μF
3 V to 5.5 V	0.1 μF	0.47 μF

Figure 1. Typical Operating Circuit and Capacitor Values

PARAMETER MEASUREMENT INFORMATION

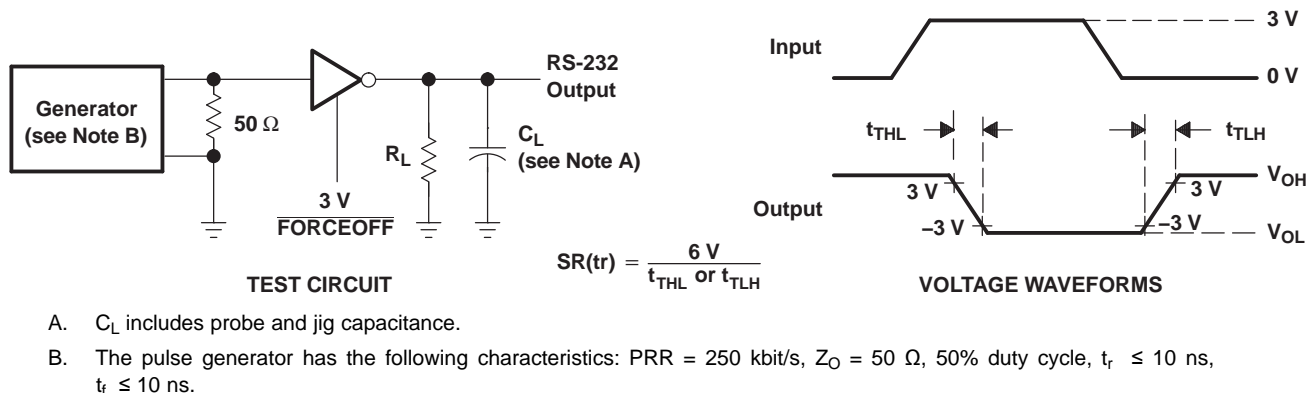


Figure 2. Driver Slew Rate

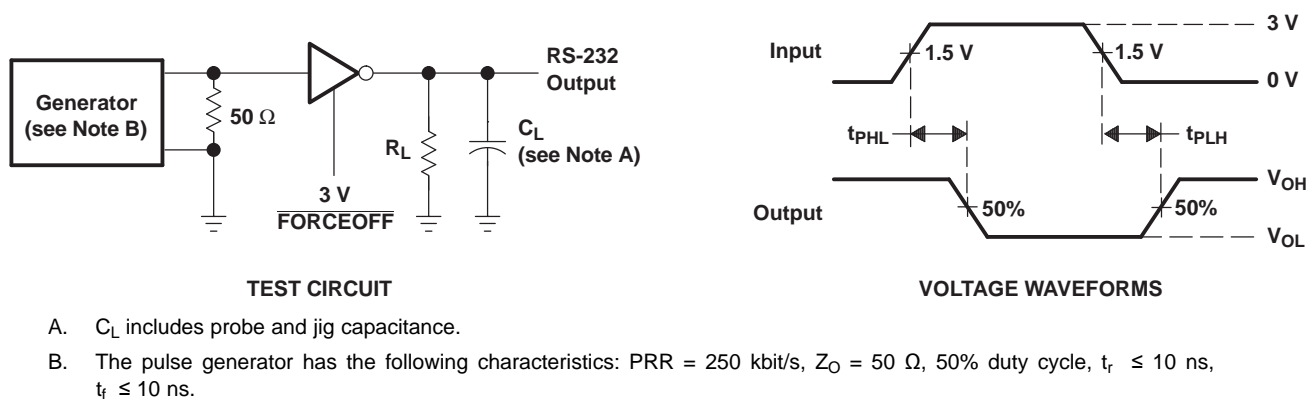


Figure 3. Driver Pulse Skew

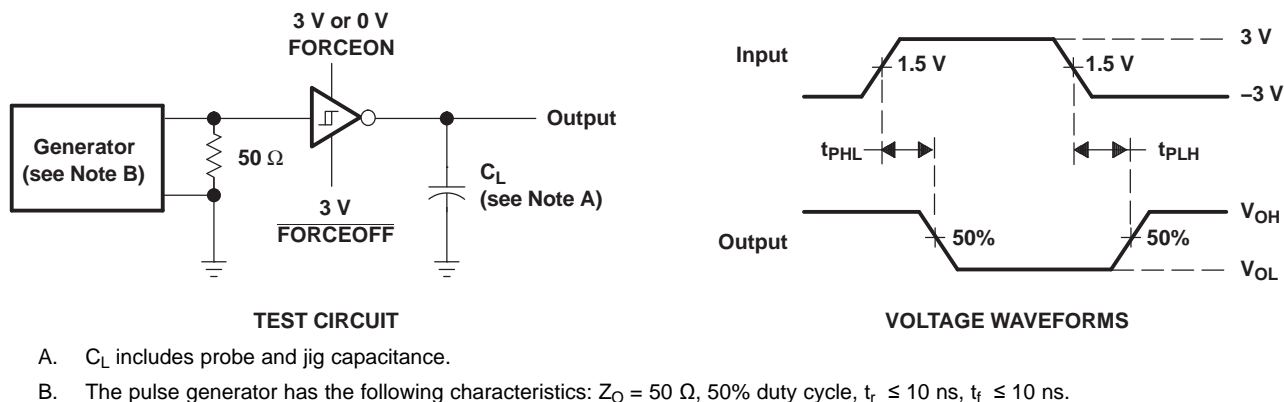
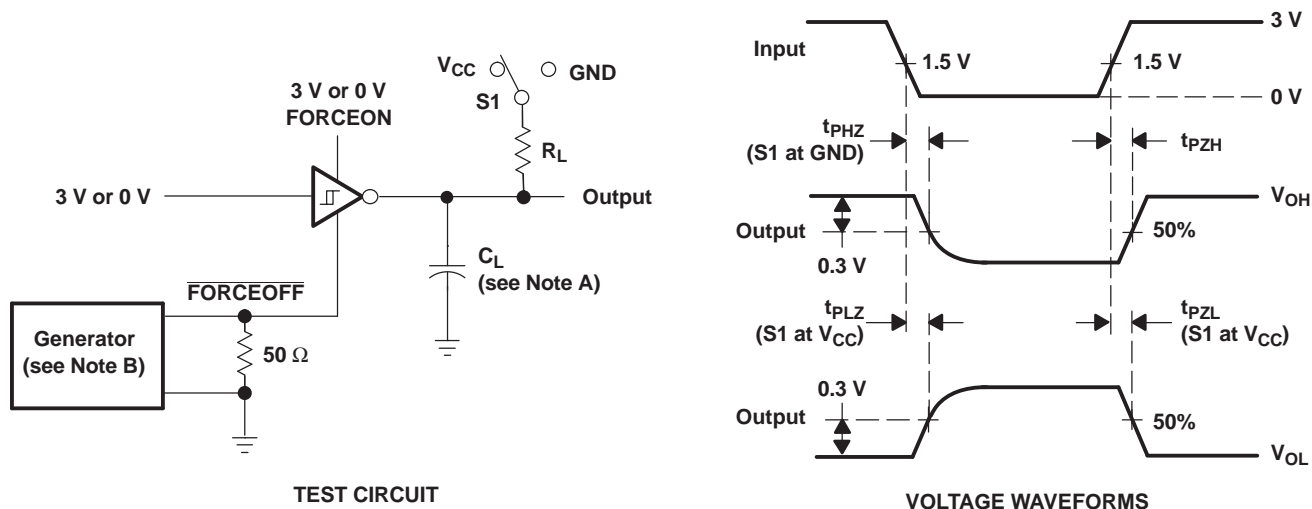


Figure 4. Receiver Propagation Delay Times

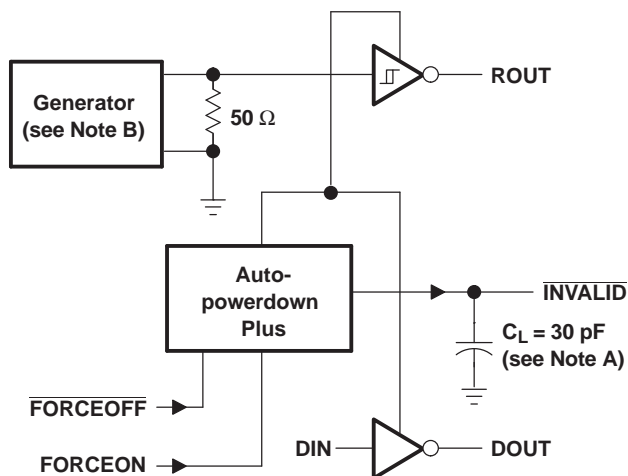
PARAMETER MEASUREMENT INFORMATION (continued)



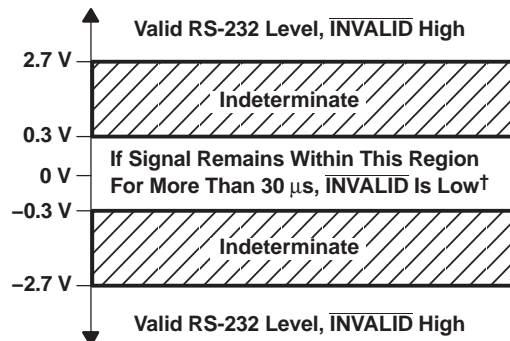
- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.
- C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- D. t_{PZL} and t_{PZH} are the same as t_{en} .

Figure 5. Receiver Enable and Disable Times

PARAMETER MEASUREMENT INFORMATION (continued)

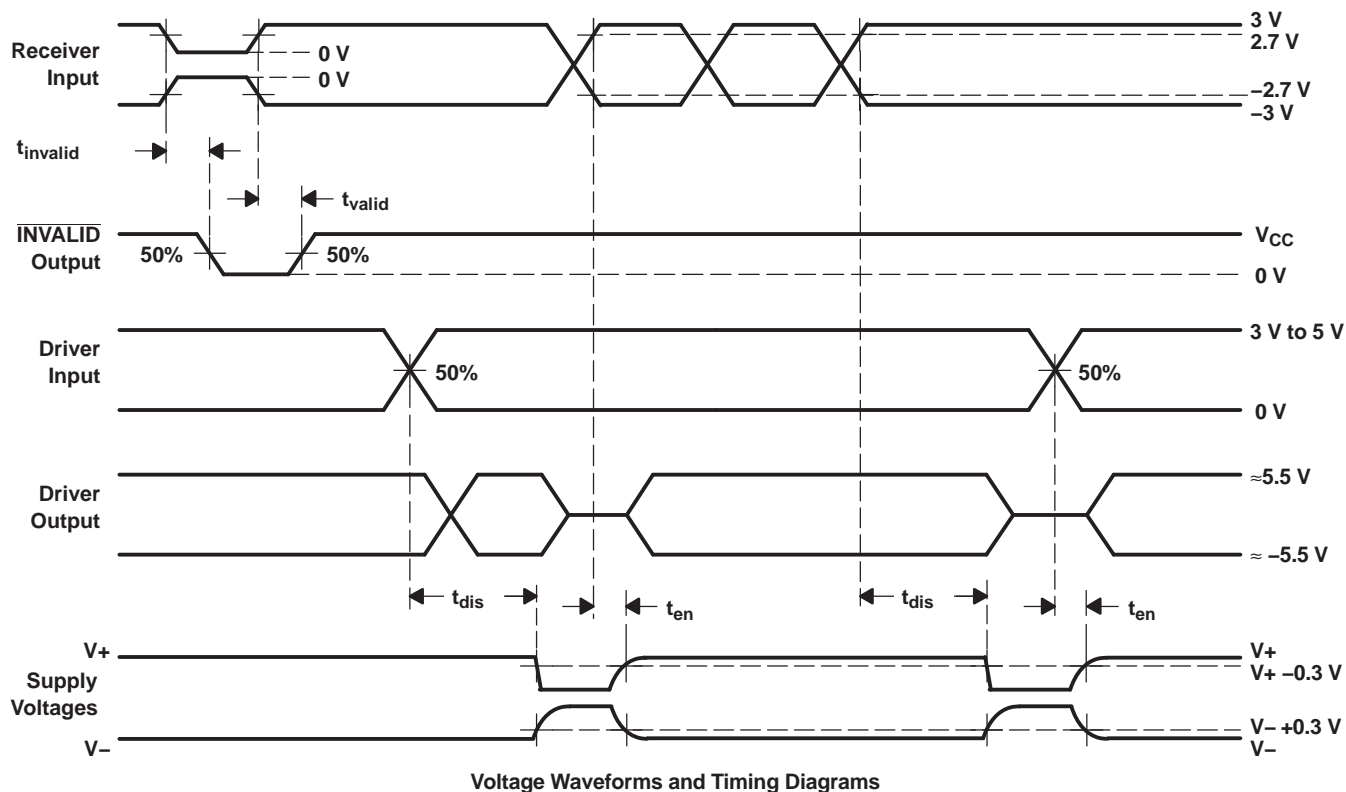


TEST CIRCUIT



[†] Auto-powerdown plus disables drivers and reduces supply current to 1 μA .

- NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.



Voltage Waveforms and Timing Diagrams

Figure 6. $\overline{\text{INVALID}}$ Propagation-Delay Times and Supply-Enabling Time

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TRS3253EIRSMR	ACTIVE	QFN	RSM	32	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TRS3253ERSMR	PREVIEW	QFN	RSM	32	3000	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

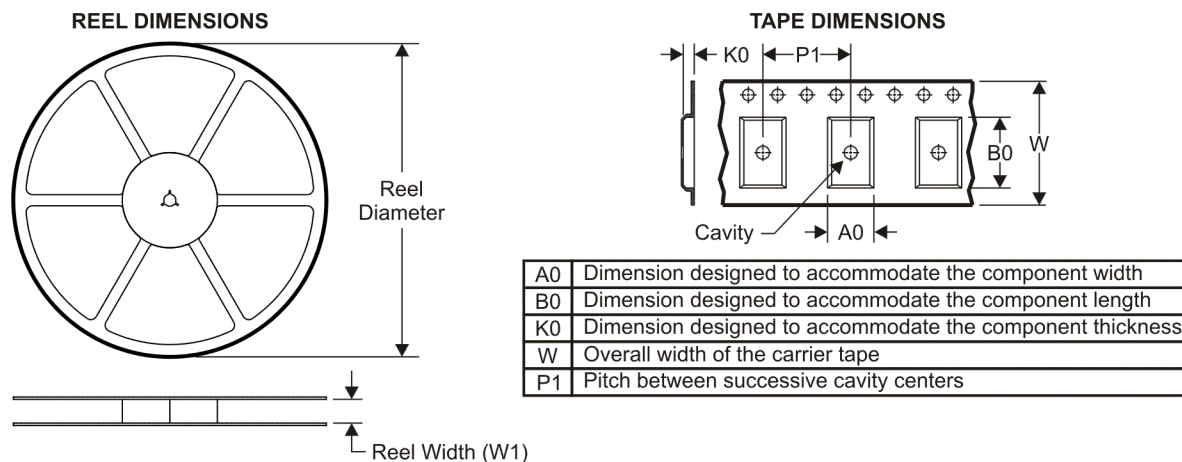
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

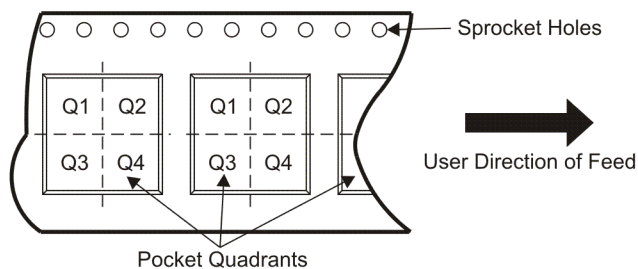
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



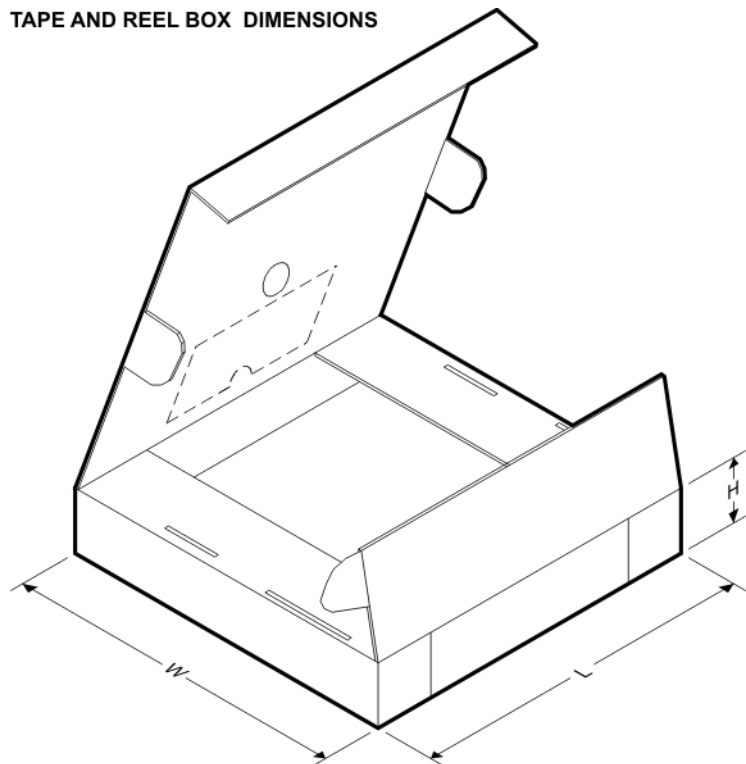
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS3253EIRSMR	QFN	RSM	32	3000	330.0	12.4	4.3	4.3	1.5	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS



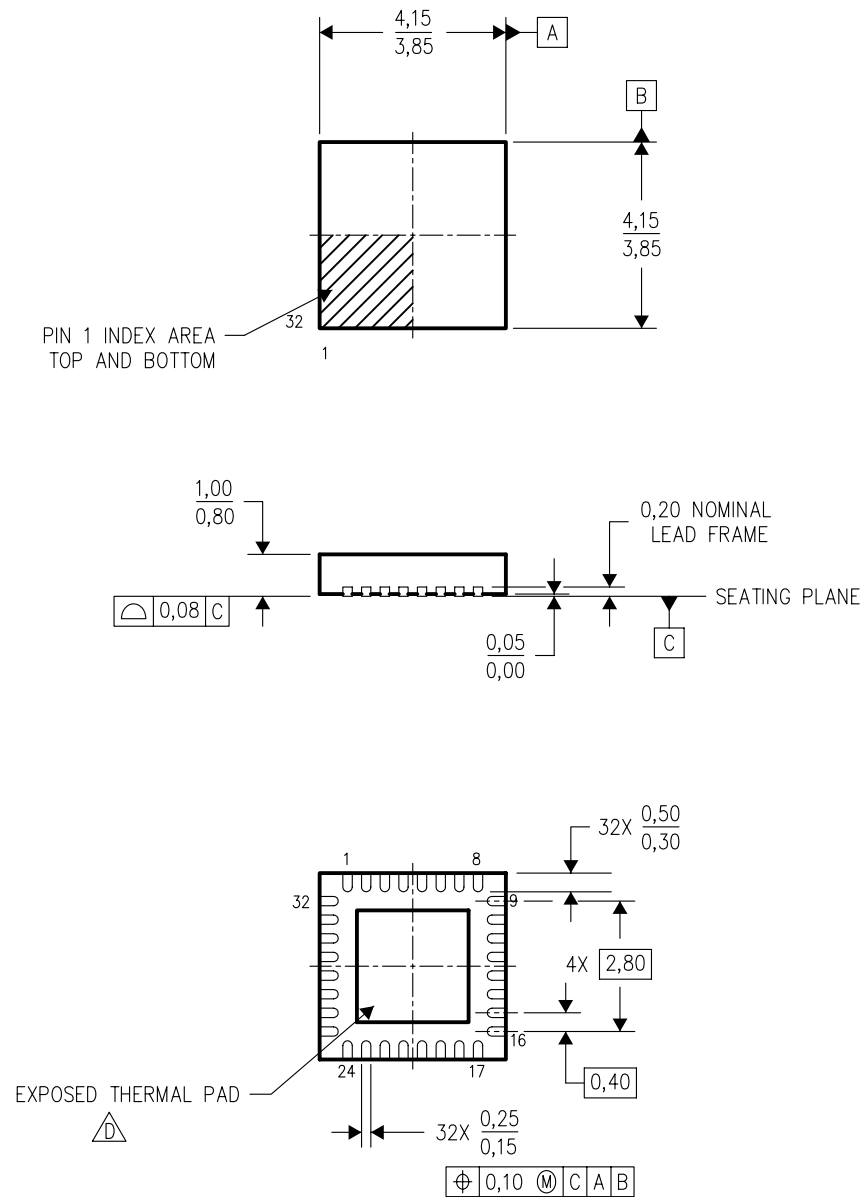
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS3253EIRSMR	QFN	RSM	32	3000	346.0	346.0	29.0


MECHANICAL DATA

RSM (S-PQFP-N32)

PLASTIC QUAD FLATPACK



4207560/A 12/05

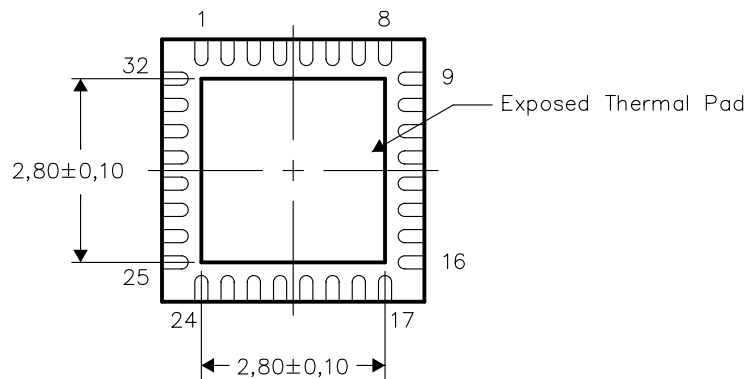
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) Package configuration.
 -  The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

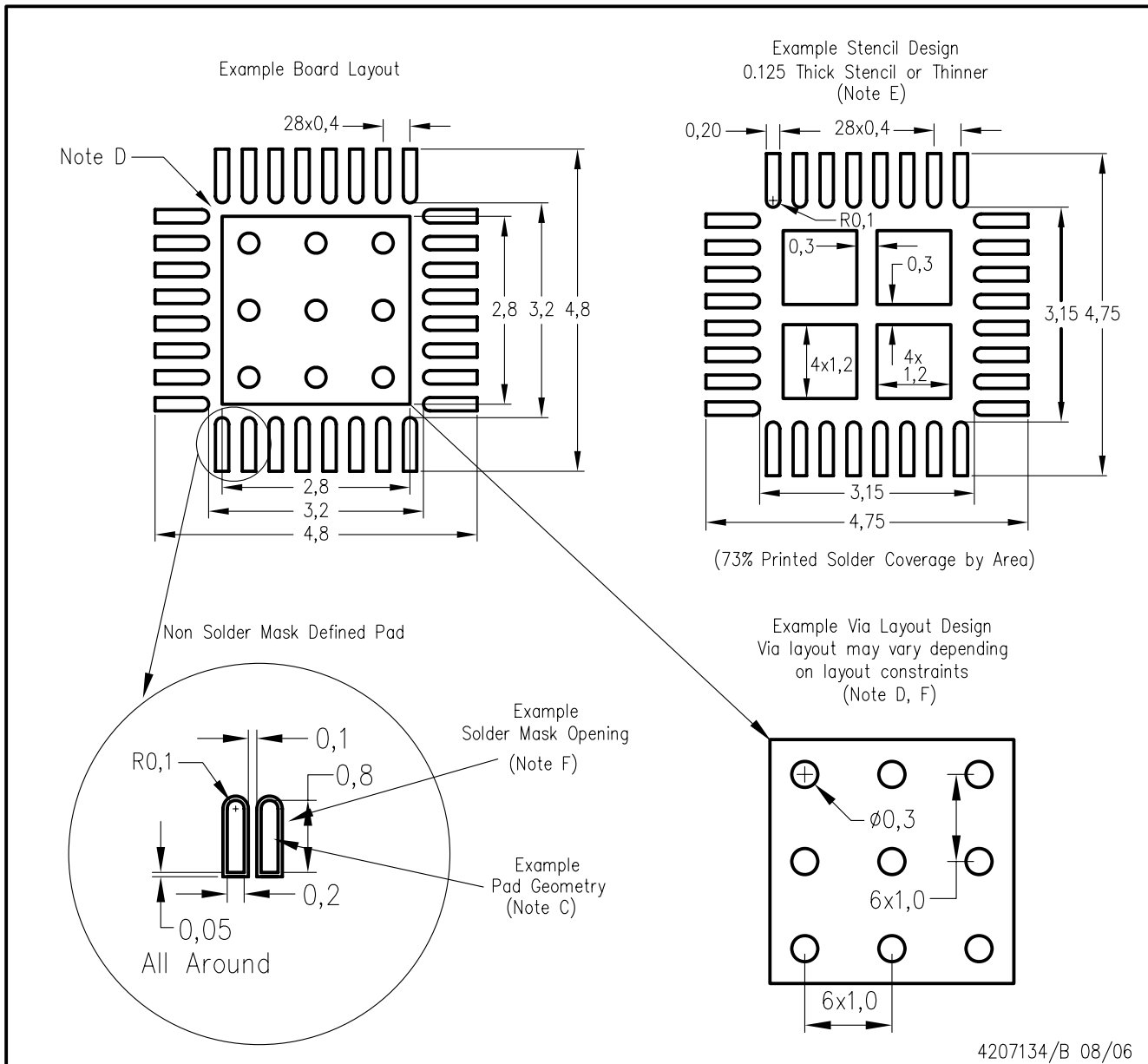


Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RSM (S-PQFP-N32)



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated